



MJ P-Channel Super Trench Power MOSFET

Description

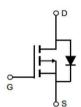
The MJ30P90G uses Super Trench technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

General Features

- $ightharpoonup V_{DS}=-30V, I_{D}=-90A$ $R_{DS(ON)}<5.1m\Omega$ (typical) @ V_{GS}=-10V $R_{DS(ON)}<7.4m\Omega$ (typical) @ V_{GS}=-4.5V
- ◆ Excellent gate charge x R_{DS(on)} product(FOM)
- ◆ Very low on-resistance R_{DS(on)}
- ◆ 150 °C operating temperature
- ◆ Pb-free lead plating
- ♦ 100% UIS tested

Application

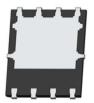
- ◆ DC/DC Converter
- ◆ Ideal for high-frequency switching and synchronous rectification











Bottom View

100% UIS TESTED! 100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJXP30P90G	MJXP30P90G	DFN5X6-8L	-	-	-

Absolute Maximum Ratings (Tc = 25 °Cunless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	-30	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lo	-90	А
Drain Current-Continuous(Tc =100°C)	ID(100°C)	-63.6	А
Pulsed Drain Current	IDM	-300	Α
Maximum Power Dissipation	Po	75	W
Single pulse avalanche energy (Note 5)	Eas	500	mJ
Derating factor		0.6	W/°C
Operating Junction and Storage Temperature Range	Тл ,Тѕтс	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	Rejc	1.0	°C/W
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Electrical Characteristics (Tc=25°C unless otherwise noted)

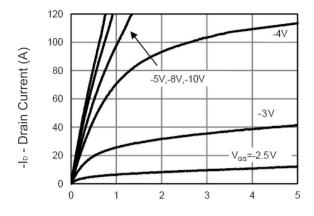
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	'					
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V I _D =-250µA	-30		-	V
Zero Gate Voltage Drain Current	loss	V _{DS} =-30V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	lgss	Vps=±20V,Vps=0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	VGS(th)	V _{DS} =V _{GS} ,I _D =-250µA	-1.0	-1.5	-2.2	V
Durin Course On Otata Desistance	Description	V _{GS} =-10V, I _D =-20A	-	5.1	5.6	mΩ
Drain-Source On-State Resistance	Rds(on)	V _{GS} =-4.5V, I _D =-20A	-	7.4	8.0	mΩ
Forward Transconductance	grs	V _{DS} =-5V,I _D =-20A	-	30	-	S
Dynamic Characteristics (Note 4)	-					-
Input Capacitance	Clss		-	3914	-	PF
Output Capacitance	Coss	V _{DS} =-15V,V _{GS} =0V, F=1.0MHz	-	1263	-	PF
Reverse Transfer Capacitance	Crss	-	-	50	-	PF
Switching Characteristics (Note 4)	,					
Turn-on Delay Time	t _{d(on)}		-	10.5	-	nS
Turn-on Rise Time	tr	- Vdd=-15V,ld=-20A	-	9	-	nS
Turn-Off Delay Time	t _{d(off)}	V _{GS} =-10V,R _G =1.6Ω	-	40	-	nS
Turn-Off Fall Time	tr	-	-	10	-	nS
Total Gate Charge	Qg		-	52	-	nC
Gate-Source Charge	Qgs	Vps=-15V,lp=-20A Vgs=-10V	-	9.6	-	nC
Gate-Drain Charge	Qgd	-	-	7.0	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	VsD	V _{GS} =0V,I _S =-20A	_		-1.2	V
Diode Forward Current (Note 2)	ls		_	_	-90	А
Reverse Recovery Time	trr	T. 0500 1 000	-		24	nS
Reverse Recovery Charge	Qrr	TJ=25°C, IF=-20A di/dt=100A/µs (Note 3)	_		68	nC

Notes:

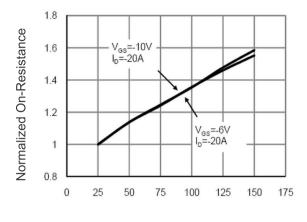
- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, t≤10sec.
- $\ \ \, \mbox{3}$ Pulse Test: Pulse Width
 $\mbox{300}\mu\mbox{s},$ Duty Cycle
 $\mbox{22}\%.$
- 4 Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics



-Vds Drain-Source Voltage (V)
Figure 1 Output Characteristics



TJ -Junction Temperature(°C)
Figure 4 Rdson-Junction Temperature

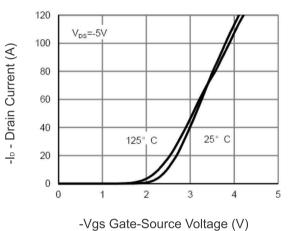
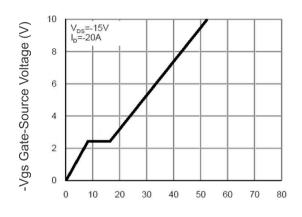


Figure 2 Transfer Characteristics



Qg Gate Charge (nC)
Figure 5 Gate Charge

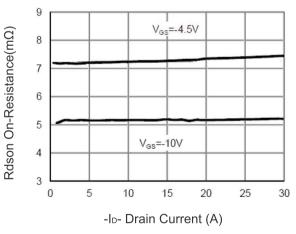


Figure 3 Rdson- Drain Current

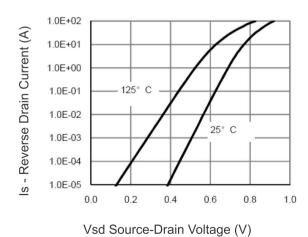


Figure 6 Drain-Source On-Resistance





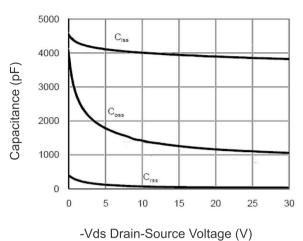
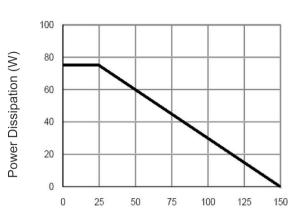


Figure 7 Capacitance vs Vds



T_J -Junction Temperature(°C)
Figure 9 Power De-rating

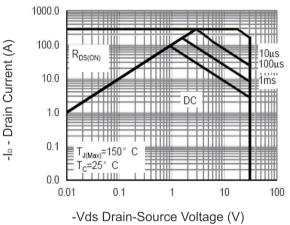
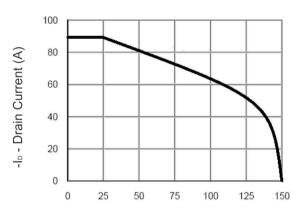
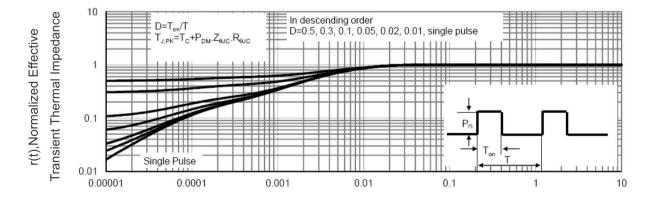


Figure 8 Safe Operation Area



T_J -Junction Temperature(°C)
Figure 10 Current De-rating



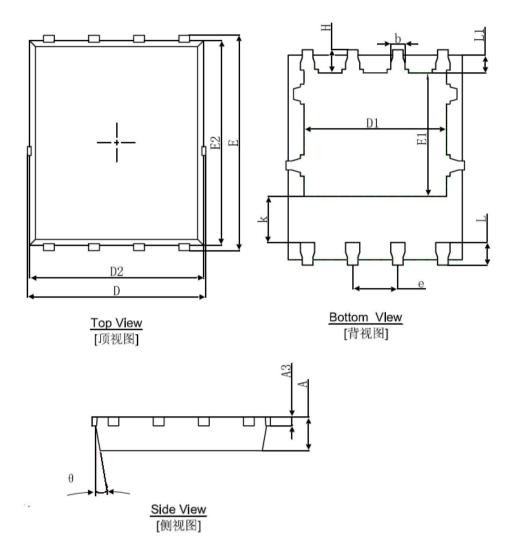
Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance





DFN5X6-8L Package Information



Complete	Dimensions I	n Millimeters	Dimension	s In Inches
Symbol	Min.	Max.	Min.	Max.
Α	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010	REF.
D	4.944	5.096	0.195	0.201
Е	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
е	1.270	TYP.	0.050	TYP.
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	8°	12°	8°	12°



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